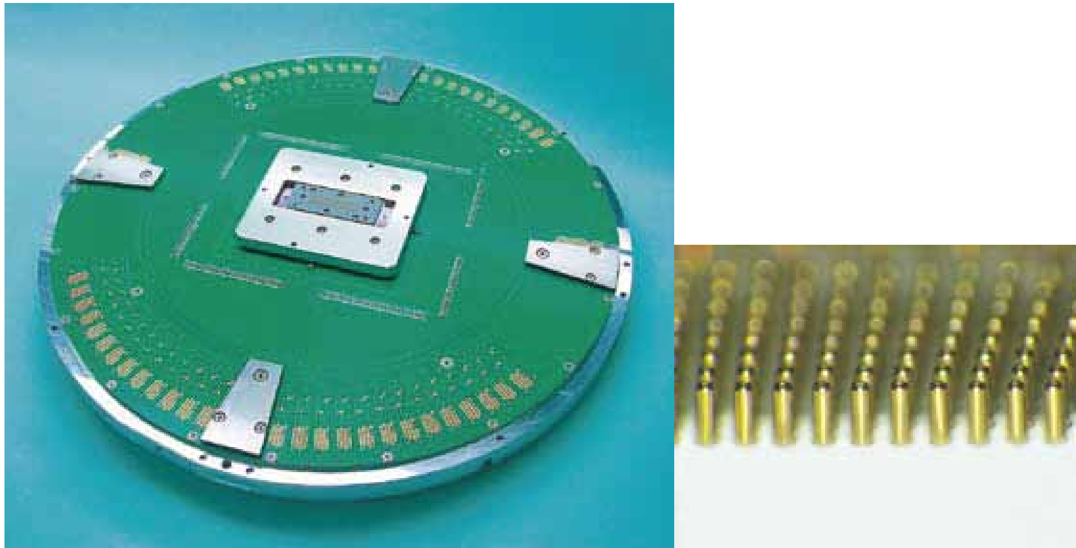
Yokowo Vertical Probe Card (YVP series)

yokowo



Yokowo Vertical Probe Card

Applications

- Solder bump and gold plating pad / Aluminum pad probing
- Wafer Level Package Single / Multi DUT probing
- Flip Chip probing

Features

- Free to define probing layout (peripherals/matrix) due to vertical contact technology.
- Contact probe is replaceable by a tweezers easily.
- Double-ended contact probe absorbs mechanical stress and prevents damage for the receptacle and wires.
- Light tuned spring force helps to reduce a risk of damage for bumps and pads.
- Original Crown type plunger exclusively developed for a solder bump assures consistent contact resistance and long life cycles time.

Specification

Min. Pitch	120μm Area Array
Material	Pd Alloy
Position Accuracy	±15μm
Planarity	30μm
Pin Force	0.049N (5gf) @100μm O.D.
Over Drive	200μm MAX 300μm
Current Carrying Capability	300mA @ φ150μm probe
Self Inductance	1.1nH @ 1GHz
Temp.	-50 ~ 125°C

[Reference] CTC Overseas Sales Dept. TEL : +81-3-3916-3116 E-mail : info-ctc@jp.yokowo.com Yokowo co., ltd.